

CLAIM AMENDMENTS:

Claim 1 (Previously Presented): A semiconductor device, comprising:

a semiconductor substrate having a circuit forming surface, and having a plurality of electrode pads provided on the circuit forming surface, said electrode pads being disposed to surround an area of the circuit forming surface;

a semiconductor element mounted within the area of the circuit forming surface;

a plurality of adhesive lines adapted for use as reference lines, said adhesive lines being disposed under the semiconductor element and on the circuit forming surface, and being respectively provided at positions corresponding to at least three corners of the semiconductor element, said adhesive lines being adapted for use as a reference for determining a correct placement of the semiconductor element within the area of the circuit forming surface, said adhesive lines adhering said semiconductor element to the circuit forming surface of said semiconductor substrate; and

a sealing resin that seals said semiconductor element;

wherein the reference lines extend beyond and outside an entire area that is sealed by said sealing resin.

Claims 2-20 (Cancelled).

Claim 21 (Previously Presented): The semiconductor device recited in claim 1, wherein a portion of the reference lines that extends beyond and outside the area that is sealed by said sealing resin is not covered by said sealing resin.

Claim 22 (New): The semiconductor device recited in claim 1, wherein the reference lines include a cross mark, and at least one rib on the cross mark, the rib corresponding to a size of the semiconductor element.

Claim 23 (New): The semiconductor device recited in claim 22, wherein the rib is disposed so that when the semiconductor element is in the correct placement within the area of the circuit forming surface, the rib is positioned under one of the at least three corners of the semiconductor element.

Claim 24 (New): The semiconductor device recited in claim 23, wherein when the rib is positioned under the one of the at least three corners of the semiconductor element, a portion of the rib is covered by the semiconductor element, and a further portion of the rib is not covered by the semiconductor element.

Claim 25 (New): The semiconductor device recited in claim 22, wherein the rib and the cross mark form an acute angle.

Claim 26 (New): The semiconductor device recited in claim 1, wherein the reference lines include a cross mark, and a plurality of ribs disposed on the cross mark and at different outward positions relative to a center of the cross mark, with each rib corresponding to a differently sized semiconductor element.

Claim 27 (New): The semiconductor device recited in claim 1, wherein the reference lines include a cross mark, and at least one frame portion at the cross mark, the frame portion corresponding to a size of the semiconductor element.

Claim 28 (New): The semiconductor device recited in claim 27, wherein the frame portion is disposed so that when the semiconductor element is in the correct placement within the area of the circuit forming surface, the frame portion is positioned under the at least three corners of the semiconductor element.

Claim 29 (New): The semiconductor device recited in claim 28, wherein when the frame portion is positioned under the at least three corners of the semiconductor element, a portion of the frame portion is covered by the semiconductor element, and a further portion of the frame portion is not covered by the semiconductor element.

Claim 30 (New): The semiconductor device recited in claim 1, wherein the reference lines include a cross mark, and a plurality of frame portions disposed on the cross mark and at different outward positions relative to a center of the cross mark, with each frame portion corresponding to a differently sized semiconductor element.

Claim 31 (New): A semiconductor device, comprising:

a semiconductor substrate having a circuit forming surface, and having a plurality of electrode pads provided on the circuit forming surface, said electrode pads being disposed to surround an area of the circuit forming surface;

a semiconductor element mounted within the area of the circuit forming surface;
a plurality of reference lines disposed under the semiconductor element and on the circuit forming surface, and being respectively provided at positions corresponding to at least three corners of the semiconductor element, said reference lines being adapted for use as a reference for determining a correct placement of the semiconductor element within the area of the circuit forming surface; and
a sealing resin that seals said semiconductor element;
wherein the reference lines extend beyond and outside an entire area that is sealed by said sealing resin.

Claim 32 (New): The semiconductor device recited in claim 31, wherein the reference lines include a cross mark, and at least one rib on the cross mark, the rib corresponding to a size of the semiconductor element.

Claim 33 (New): The semiconductor device recited in claim 32, wherein the rib is disposed so that when the semiconductor element is in the correct placement within the area of the circuit forming surface, the rib is positioned under one of the at least three corners of the semiconductor element.

Claim 34 (New): The semiconductor device recited in claim 33, wherein when the rib is positioned under the one of the at least three corners of the semiconductor element, a portion of the rib is covered by the semiconductor element, and a further portion of the rib is not covered by the semiconductor element.

Claim 35 (New): The semiconductor device recited in claim 32, wherein the rib and the cross mark form an acute angle.

Claim 36 (New): The semiconductor device recited in claim 31, wherein the reference lines include a cross mark, and a plurality of ribs disposed on the cross mark and at different outward positions relative to a center of the cross mark, with each rib corresponding to a differently sized semiconductor element.

Claim 37 (New): The semiconductor device recited in claim 31, wherein the reference lines include a cross mark, and at least one frame portion at the cross mark, the frame portion corresponding to a size of the semiconductor element.

Claim 38 (New): The semiconductor device recited in claim 37, wherein the frame portion is disposed so that when the semiconductor element is in the correct placement within the area of the circuit forming surface, the frame portion is positioned under the at least three corners of the semiconductor element.

Claim 39 (New): The semiconductor device recited in claim 38, wherein when the frame portion is positioned under the at least three corners of the semiconductor element, a portion of the frame portion is covered by the semiconductor element, and a further portion of the frame portion is not covered by the semiconductor element.

Claim 40 (New): The semiconductor device recited in claim 31, wherein the reference lines include a cross mark, and a plurality of frame portions disposed on the cross mark and at different outward positions relative to a center of the cross mark, with each frame portion corresponding to a differently sized semiconductor element.